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(54) CONDUCTIVE PASTE AND CERAMIC BOARD

(57) Abstract:

PROBLEM TO BE SOLVED: To provide conductive paste by which no occurrence of structure defect is allowed, and provide a ceramic board which is provided with a conductive circuit pattern formed by using the conductive paste, particularly with a via hole.

SOLUTION: Conductive paste is formed by dispersing Cu powder in an organic vehicle, the Cu powder is composed of spherical first Cu powder whose particle diameter is within the range of 0.1 to 50 μ m and flat second Cu

powder, a mixing ratio against the whole paste is set to be within the range of 50 to 90 percentage by weight, and the mixing ratio of the second Cu powder in the whole Cu powder is set to be 10 percentage by weight or more. The sintered body of conductive metal which is composed of the spherical first Cu powder the particle diameter of which is within the range of 0.1 to 50 μ m and the flat second Cu powder and in which the mixing ratio of the second Cu powder in the whole Cu powder is 10 percentage by weight or more is filled in the via hole of the ceramic board.

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